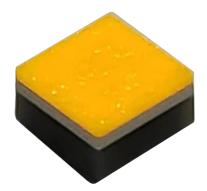
Flip-Chips · Planar Package 倒装芯片 · 平面封装 Single Color LEDs 单色光源

Main Applications:

主要应用领域:

- high power head lighting for cars, motorcycles, trucks, trains, ships, planes, etc.
 - 大功率前照头灯照明,适用于汽车,摩托车,卡车,火车,船舰,飞机 等
- ✓ directional projection and beam lighting with small angle for projection, light beam, dyeing, pattern, audience, business, hotel, museum, etc. 小角度方向性投射类照明,适用于投射,光束,染色,图案,观众,商业,酒店,博物馆等
- ✓ wearable head lighting for civilians, soldier and policeman 民用军用警用可穿戴头灯照明
- ✓ portable strong light and blinding lighting 便携式强光与致盲照明
- ✓ flash lighting 闪光照明
- ✓ medical and micro-instrument lighting 医疗与显微器械照明

S1281 etc



Main Parameters	Typical Values
Voltage (V)	TR- R 2 Others 3
Current (mA)	700
Max. Power (W) Note	3.1
LES (mm)	2.0x2.0
CCT (K) / Ra	N/A
Color / Dominant Wavelength (nm)	S1286 TR-R 617.5-627.5 S1285 TR-G / 520-530 S1284 TR-C / 485-495 S1283 TR-B / 450-460 S1282 TR-B / 465-475 S1281 PC-A / 1600-1800 S1280 PC-L / 4150-4400 S1403 WW 2580-2870 / >96 S1402 CW 7000-7500 / >96
Matched Cu Board	N/A

Note: The maximum power only for reference and related to the heat dissipation power of the radiator, the thermal resistance between the radiator and the light source and the ambient temperature.

Main Features

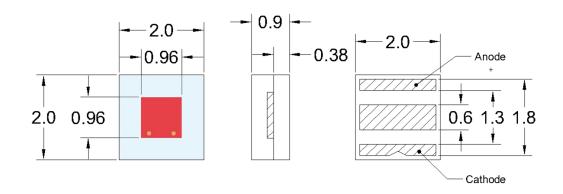
Low Power Single Color Integrated Lighting Source;

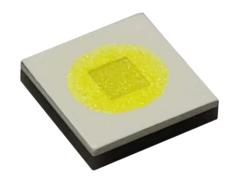
Planar Package Using AIN Ceramic Substrate for Low Heat Resistance;

Natural Chip Emitting Colors, High Color Purity and Consistency;

Other Power, LES, Color Combination, CCT and Ra Available on Request;

Applicable to High End Color Mixing Intelligent Lighting.





Main Parameters	Typical Values
Voltage (V)	3
Current (mA)	700
Max. Power (W) Note	3
LES (mm)	2.45
CCT (K) /Ra	6500-7000
Color / Dominant Wavelength (nm)	N/A
Matched Cu Board	H001-2020

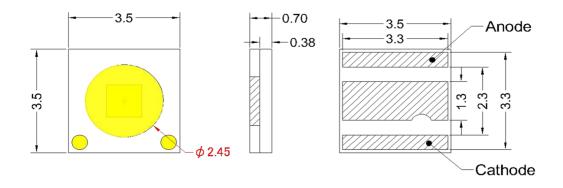
Main Features

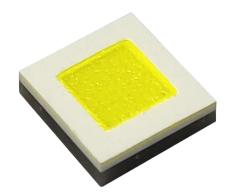
Low Power Single Color Integrated Lighting Source;

Planar Package Using AIN Ceramic Substrate for Low Heat Resistance;

Flip Chips with No Gold Wires for High Integration & Good Reliability;

Other Power, LES, Color Combination, CCT and Ra Available on Request;





Main Parameters	Typical Values
Voltage (V)	3
Current (mA)	1925
Max. Power (W) Note	8.6
LES (mm)	2.4x2.4
CCT (K) / Ra	5500-6500
Color / Dominant Wavelength (nm)	N/A
Matched Cu Board	H001-2020

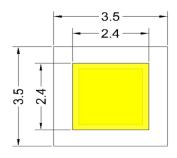
Main Features

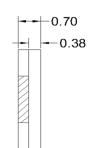
Low Power Single Color Integrated Lighting Source;

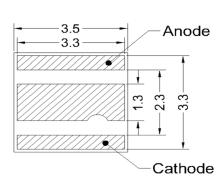
Planar Package Using AIN Ceramic Substrate for Low Heat Resistance;

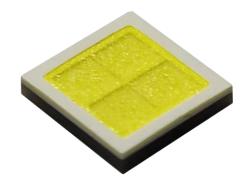
Flip Chips with No Gold Wires for High Integration & Good Reliability;

Other Power, LES, Color Combination, CCT and Ra Available on Request;









Main Parameters	Typical Values
Voltage (V)	12
Current (mA)	775
Max. Power (W) Note	12.1
LES (mm)	2.7x2.7
CCT (K) /Ra	6020-7040
Color / Dominant Wavelength (nm)	N/A
Matched Cu Board	H001-2020

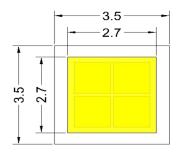
Main Features

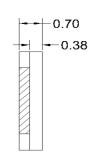
Low Power Single Color Integrated Lighting Source;

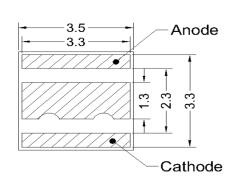
Planar Package Using AIN Ceramic Substrate for Low Heat Resistance;

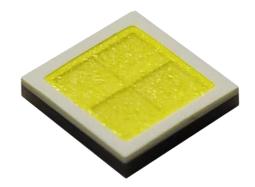
Flip Chips with No Gold Wires for High Integration & Good Reliability;

Other Power, LES, Color Combination, CCT and Ra Available on Request;









Main Parameters	Typical Values
Voltage (V)	3
Current (mA)	2725
Max. Power (W) Note	12.1
LES (mm)	2.7x2.7
CCT (K) / Ra	6020-7040
Color / Dominant Wavelength (nm)	N/A
Matched Cu Board	H001-2020

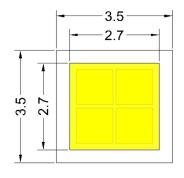
Main Features

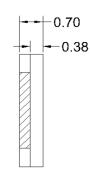
Low Power Single Color Integrated Lighting Source;

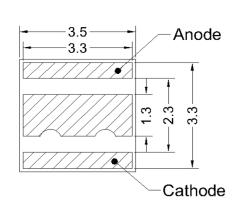
Planar Package Using AIN Ceramic Substrate for Low Heat Resistance;

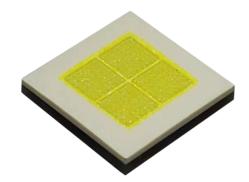
Flip Chips with No Gold Wires for High Integration & Good Reliability;

Other Power, LES, Color Combination, CCT and Ra Available on Request;









Main Parameters	Typical Values
Voltage (V)	3
Current (mA)	5075
Max. Power (W) Note	19.8
LES (mm)	3.3x3.3
CCT (K) /Ra	7690-8350
Color / Dominant Wavelength (nm)	N/A
Matched Cu Board	H003-2020 H013-1818 H041-1818 H063-3333

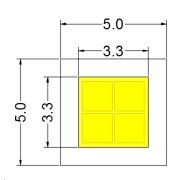
Main Features

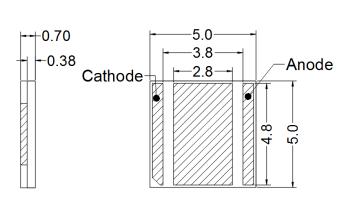
Low Power Single Color Integrated Lighting Source;

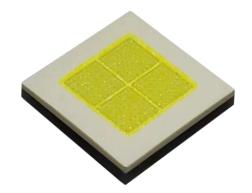
Planar Package Using AIN Ceramic Substrate for Low Heat Resistance;

Flip Chips with No Gold Wires for High Integration & Good Reliability;

Other Power, LES, Color Combination, CCT and Ra Available on Request;







Main Parameters	Typical Values
Voltage (V)	6
Current (mA)	2550
Max. Power (W) Note	19.8
LES (mm)	3.3x3.3
CCT (K) /Ra	7690-8350
Color / Dominant Wavelength (nm)	N/A
Matched Cu Board	H003-2020 H013-1818 H041-1818 H063-3333

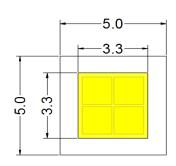
Main Features

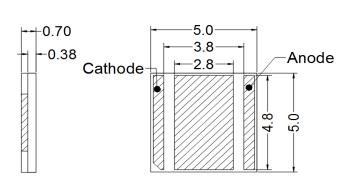
Low Power Single Color Integrated Lighting Source;

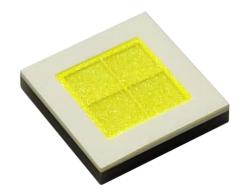
Planar Package Using AIN Ceramic Substrate for Low Heat Resistance;

Flip Chips with No Gold Wires for High Integration & Good Reliability;

Other Power, LES, Color Combination, CCT and Ra Available on Request;







Main Parameters	Typical Values
Voltage (V)	12
Current (mA)	1275
Max. Power (W) Note	19.8
LES (mm)	3.3x3.3
CCT (K) /Ra	7690-8350
Color / Dominant Wavelength (nm)	N/A
Matched Cu Board	H003-2020 H013-1818 H041-1818 H063-3333

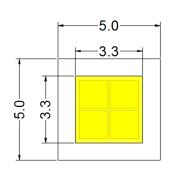
Main Features

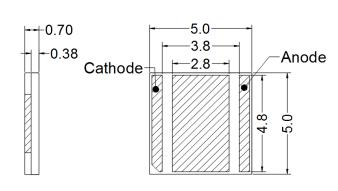
Low Power Single Color Integrated Lighting Source;

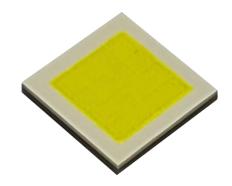
Planar Package Using AIN Ceramic Substrate for Low Heat Resistance;

Flip Chips with No Gold Wires for High Integration & Good Reliability;

Other Power, LES, Color Combination, CCT and Ra Available on Request;







Main Parameters	Typical Values
Voltage (V)	12
Current (mA)	3400
Max. Power (W) Note	48
LES (mm)	5.26x5.26
CCT (K) / Ra	7690-8350
Color / Dominant Wavelength (nm)	N/A
Matched Cu Board	H004-2020 H010-2020 H015-1818 H018-2728 H030-1818

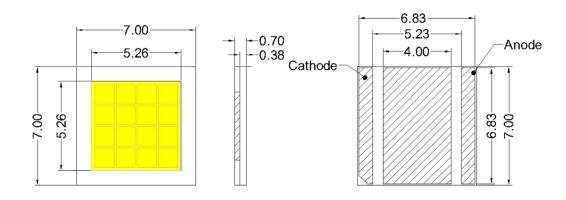
Main Features

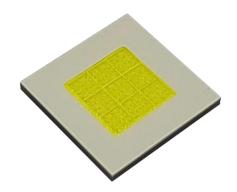
Low Power Single Color Integrated Lighting Source;

Planar Package Using AIN Ceramic Substrate for Low Heat Resistance;

Flip Chips with No Gold Wires for High Integration & Good Reliability;

Other Power, LES, Color Combination, CCT and Ra Available on Request;





Main Parameters	Typical Values
Voltage (V)	27
Current (mA)	825
Max. Power (W) Note	26.5
LES (mm)	4.0x4.0
CCT (K) / Ra	7690-8350
Color / Dominant Wavelength (nm)	N/A
Matched Cu Board	H004-2020 H010-2020 H015-1818 H018-2728 H030-1818

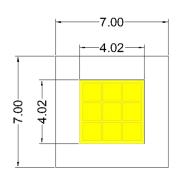
Main Features

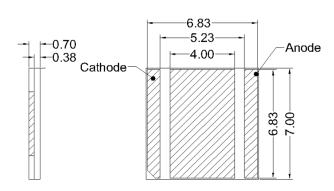
Low Power Single Color Integrated Lighting Source;

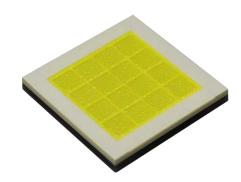
Planar Package Using AIN Ceramic Substrate for Low Heat Resistance;

Flip Chips with No Gold Wires for High Integration & Good Reliability;

Other Power, LES, Color Combination, CCT and Ra Available on Request;







Main Parameters	Typical Values
Voltage (V)	24
Current (mA)	1650
Max. Power (W) Note	47
LES (mm)	5.2x5.2
CCT (K) / Ra	8350-9000
Color / Dominant Wavelength (nm)	N/A
Matched Cu Board	H004-2020 H010-2020 H015-1818 H018-2728 H030-1818

Main Features

Low Power Single Color Integrated Lighting Source;

Planar Package Using AIN Ceramic Substrate for Low Heat Resistance;

Flip Chips with No Gold Wires for High Integration & Good Reliability;

Other Power, LES, Color Combination, CCT and Ra Available on Request;

